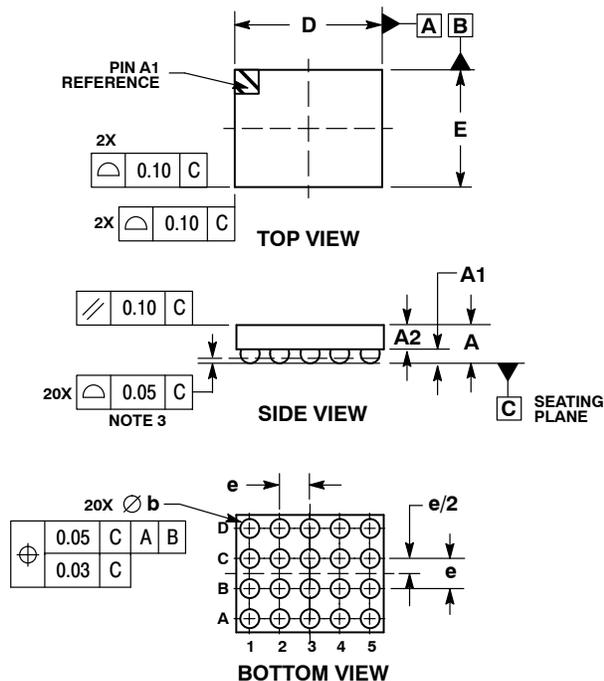




20 PIN FLIP-CHIP, 2.5x2.0, 0.5P  
CASE 499BH  
ISSUE A

DATE 22 OCT 2010

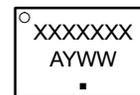
SCALE 4:1



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  2. CONTROLLING DIMENSION: MILLIMETERS.
  3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.
  4. DIE COAT, 0.04 THICK, PERMISSIBLE ON THIS SURFACE. DIE COAT THICKNESS IS INCLUDED IN DIMENSIONS A AND A2.

DIM	MILLIMETERS	
	MIN	MAX
A	0.54	0.66
A1	---	0.27
A2	0.33	0.39
b	0.29	0.34
D	2.50 BSC	
E	2.00 BSC	
e	0.50 BSC	

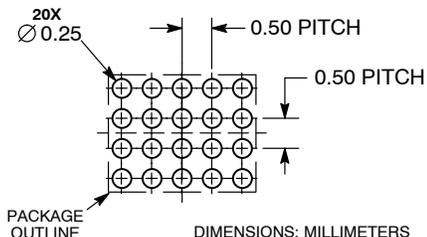
GENERIC MARKING DIAGRAM\*



- XXXXXXX = Specific Device Code
- A = Assembly Location
- Y = Year
- WW = Work Week
- = Pb-Free Package

\*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

RECOMMENDED SOLDER FOOTPRINT\*



\*For additional information on our Pb-Free strategy and soldering details, please download the onsemi Soldering and Mounting Techniques Reference Manual, [SOLDERRM/D](#).

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DESCRIPTION:	20 PIN FLIP-CHIP, 2.5 X 2.0, 0.5P	PAGE 1 OF 1

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